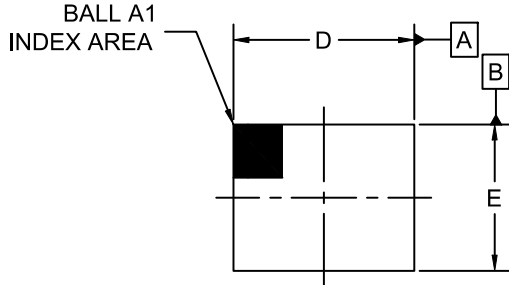


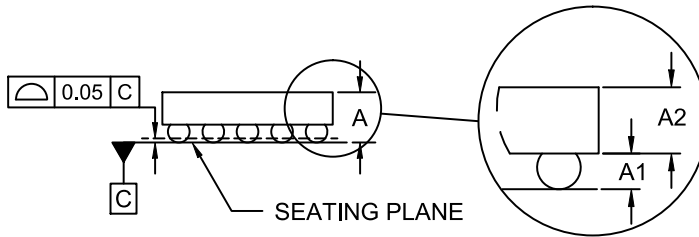


WLCSP20 2.2x1.8x0.574
CASE 567UT
ISSUE O

DATE 07 JUL 2017



TOP VIEW



SIDE VIEW

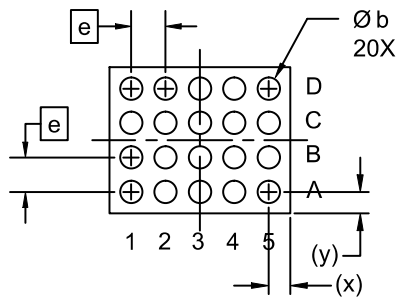
DETAIL A

NOTES:

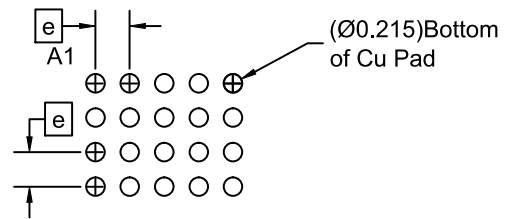
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	.536	.574	.612
A1	.176	.196	.216
A2	.360	.378	.396
b	.240	.260	.280
D	2.170	2.200	2.230
E	1.770	1.800	1.830
e	0.40 BSC		
x	0.285	0.300	0.315
y	0.285	0.300	0.315

$\oplus 0.005(M) C A B$



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT (NSMD PAD TYPE)

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DESCRIPTION:	WLCSP20 2.2x1.8x0.574	PAGE 1 OF 1

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